

PCN # 229

Initial Notification Date:

December 13, 2021

Product / Process Change Notice

Parts Affected:

Power transistor chip processes CP230 (NPN) and CP630 (PNP), wafers and bare die.

Extent of Change:

Complementary wafer processes CP230 (NPN) and CP630 (PNP) have been discontinued and are being replaced with CP260 (NPN) and CP660 (PNP) wafer processes. See figures 1 and 2 for details.

Reason for Change:

Wafer processes CP230 and CP630 are being replaced by wafer processes CP260 and CP660, respectively, to enhance manufacturing process controls and performance. In addition, this change is being made to ensure an undisrupted supply of product, moving forward.

Effect of Change:

Replacement wafer processes CP260 (NPN) and CP660 (PNP) meet all electrical specifications of original wafer processes CP230 (NPN) and CP630 (PNP), for the individual devices listed below.

Qualification:

Based on JESD22 and MIL-STD-750 standards, qualification testing is currently in-process. And data will be provided when completed, approximately end Q4-2021.

Earliest Effective Date of Change:

To be determined after completion of qualification testing.

Part Numbers Affected:

NPN

CP230-2N6039-CM
CP230-2N6039-CT
CP230-2N6039-WN
CP230-CZT122-CT
CP230-CZT122-WN
CP230-H2N6039-CM
CP230-KTIP122-CM
CP230-TIP122-CM
CP230-TIP122-CT
CP230-TIP122-CT20
CP230-TIP122-WN

PNP

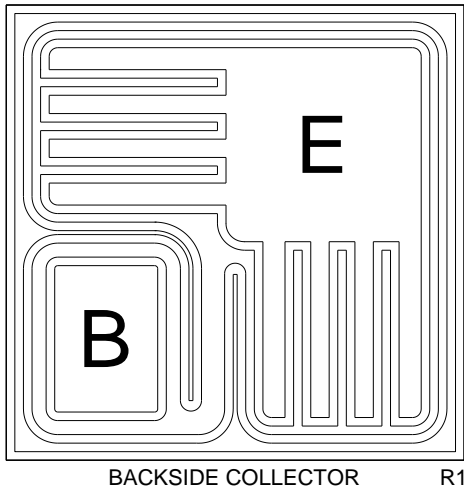
CP630-2N6036-CT
CP630-2N6036-WN
CP630-CEN1263-WN
CP630-CZT127-CT
CP630-TIP127-CT
CP630-TIP127-WN
CP630-TIP127-WR
CZT127

CZT122

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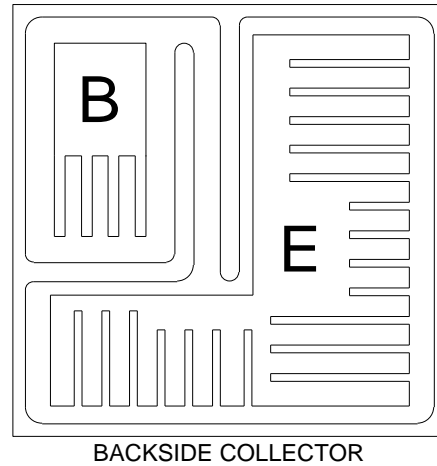
Figures:

Figure 1: CP230 / CP630 Chip Geometry (Discontinued)



Wafer Diameter: 4 inch
Die Size: 80 x 80 mils
Die Thickness: 8.0 mils
Bond Pad Size (Emitter): 34 x 34 mils
Bond Pad Size (Base): 18 x 27 mils
Topside Metal: Al (30,000Å)
Backside Metal: Ti/Pd/Ag (20,000Å)

Figure 2: CP260 / CP660 Chip Geometry



Wafer Diameter: 4 inch
Die Size: 71 x 71 mils
Die Thickness: 9.4 mils
Bond Pad Size (Emitter): 15 x 21 mils
Bond Pad Size (Base): 15 x 19 mils
Topside Metal: Al (42,500Å)
Backside Metal: Ag (12,000Å)



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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	